ABSTRACT

This user’s guide provides a description as well as directions for the use of UCC12050EVM-022 to evaluate the UCC120xy family of isolated, high frequency, integrated transformer, DC/DC converter modules from Texas Instruments. This EVM allows designers to quickly and efficiently evaluate the UCC120xy for use in electrically isolated system designs. The EVM comes with UCC12050DVE populated by default but can accommodate any of the pin-to-pin compatible, alternate versions listed in Table 1-1. The UCC12050DVE is the default descriptive part number used throughout this document.

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1 Introduction

The UCC12050DVE is a high efficiency, low-emissions, 5 kVRms Isolated DC/DC Converter Module capable of delivering up to 500 mW of power to isolated applications. Since the UCC12050DVE provides isolated power in an integrated package, this allows systems to reduce cost and size by removing the need for separate isolated power supplies. The UCC12050DVE delivers class-leading efficiency in power conversion from the primary to the secondary side while removing the need for bulky external transformer or power modules common in current designs. This integration allows for a much smaller area as well as a much shorter profile when compared to industry standards for power isolation techniques used in the field today. The UCC12050DVE is the default IC used in this EVM but any of the versions listed in Table 1-1 can be used for evaluation. Each of the component versions listed in Table 1-1 are pin-to-pin compatible, functionally equivalent, drop in replacements with respect to one another.

Table 1-1. UCC120xy IC Version Differences

<table>
<thead>
<tr>
<th>Part Number</th>
<th>Isolation/Surge/Working Voltage</th>
<th>Automotive Qualification</th>
</tr>
</thead>
<tbody>
<tr>
<td>UCC12040DVE</td>
<td>3 kVRMS/6.5 kVPK/850 VRMS</td>
<td>No</td>
</tr>
<tr>
<td>UCC12050DVE</td>
<td>5 kVRMS/10 kVPK/1.2 kVRMS</td>
<td>No</td>
</tr>
<tr>
<td>UCC12041QDVERQ1</td>
<td>3 kVRMS/6.5 kVPK/850 VRMS</td>
<td>Yes, AEC-Q100</td>
</tr>
<tr>
<td>UCC12051QDVERQ1</td>
<td>5 kVRMS/10 kVPK/1.2 kVRMS</td>
<td>Yes, AEC-Q100</td>
</tr>
</tbody>
</table>
2 Description

The UCC12050EVM-022 is intended to allow designers to evaluate the performance characteristics and abilities of the UCC12050DVE quickly and easily for use in isolated systems. The EVM allows users to test functions of the UCC12050DVE such as: Enable/Disable the device easily, Sync the device with an external clock source, detect potential external clock faults, select 5 V or 5.4 V output modes, and easily apply variable resistive loads to the output.

This EVM allows the user to easily measure efficiency across the input voltage range and varying output loads that the system might require. Section 5 documents how to make connections and measurements for testing efficiency across varying loads. Another feature of this EVM is the test points, which are labeled as TP1, TP2 and TP3, specially intended for use with oscilloscope probe ground springs, also known as *pig tails*, for measuring small signals such as input/output ripple voltages.
3 Typical Application Circuit and Top Component View

Figure 3-1 shows the typical application circuit for UCC12050DVE.

![Typical application circuit for UCC12050DVE](image)

**Figure 3-1. Typical application circuit**

Figure 3-2 shows a top view picture of the EVM.

![Top view of UCC12050EVM-022 Rev. A](image)

**Figure 3-2. Top view of UCC12050EVM-022 Rev. A**
4 Pin Configuration and Pin Functions

DVE Package 16-Pin SOIC Top View

4.1 Pin Functions

<table>
<thead>
<tr>
<th>PIN</th>
<th>I/O(1)</th>
<th>DESCRIPTION</th>
</tr>
</thead>
<tbody>
<tr>
<td>NAME</td>
<td>NO.</td>
<td></td>
</tr>
<tr>
<td>EN</td>
<td>1</td>
<td>Active-high enable input. Connect EN to GNDP to disable the device. Connect EN to VINP to enable the device. EN should be in the desired state (enabled/disabled) prior to power up.</td>
</tr>
<tr>
<td>GNDP</td>
<td>2</td>
<td>Ground return for primary side supply (VINP).</td>
</tr>
<tr>
<td>VINP</td>
<td>3</td>
<td>Primary side input supply voltage input. Connect a 10-μF ceramic capacitor between VINP and GNDP, close to the device pins, for proper operation. Connect a 0.1μF ceramic capacitor in parallel with the 10μF for additional high frequency filtering.</td>
</tr>
<tr>
<td>SYNC</td>
<td>4</td>
<td>Synchronous clock input pin. Provide a clock signal to synchronize multiple UCC12050 devices or connect to GNDP for standalone operation using the internal oscillator. If the SYNC pin is left open it should be separated from any switching noise to avoid false clock coupling.</td>
</tr>
<tr>
<td>SYNC_OK</td>
<td>5</td>
<td>Active-low, open-drain diagnostic output. Pin is asserted LOW if no external SYNC clock or one that is outside of the operating range of the UCC12050 is detected. In this state, the external clock is ignored and the DC/DC converter is clocked by the device's internal oscillator. The pin is in high-impedance if a good clock is applied on SYNC.</td>
</tr>
<tr>
<td>NC</td>
<td>6, 7, 8</td>
<td>No internal connection. Connect NC to GNDP on printed circuit board.</td>
</tr>
<tr>
<td>GNDNS</td>
<td>9, 15, 16</td>
<td>Ground return for secondary side (VISO).</td>
</tr>
<tr>
<td>NC</td>
<td>10, 11, 12</td>
<td>No internal connection. Connect NC to GNDNS on printed circuit board.</td>
</tr>
<tr>
<td>SEL</td>
<td>13</td>
<td>VISO regulation voltage selection input. VISO regulation is selectable between 3.3V, 3.7V, 5.0V, and 5.4V using the SEL input. See for more details using SEL to select the VISO regulation threshold.</td>
</tr>
<tr>
<td>VISO</td>
<td>14</td>
<td>Isolated supply voltage output. Connect a 10-μF ceramic capacitor between VISO and GNDNS, close to the device pins, for proper operation. Connect a 0.1μF ceramic capacitor in parallel with the 10μF for additional high frequency filtering.</td>
</tr>
</tbody>
</table>

(1) P = Power, G = Ground, I = Input, O = Output
5 EVM Setup and Operation

5.1 U1 Component Selection

This EVM comes with UCC12050DVE installed in the U1 reference designator position. Any of the alternate versions listed in Table 1-1 can be exchanged in place of UCC12050DVE. If U1 replacement is required, it is recommended to always use best practice soldering techniques. This can include taking appropriate ESD precautions and having qualified personnel, skilled at surface mount soldering and board level rework, removing and installing U1. Visually verify the desired UCC120xy component version is properly installed in the EVM. If rework on U1 has previously been performed, visually verify correct orientation of U1 according to Figure 3-2. The pin 1 locating dot on top of the IC package should be oriented at the top left according to Figure 3-2.

5.2 External Connections for Easy Evaluation

The UCC12050EVM-022 EVM utilizes screw terminals for quickly connecting to VINP and VISO. Connect a +5 V supply (+4.5 V to +5.5 V) between VINP and GNDP of J1 to supply power to the board. Connect a variable load between VISO and GNDS of J6. Alternatively, R4 is available to solder down a load resistor directly to the board. It is recommended to use an 0805 resistor that is rated for 0.5 W or greater. The value depends on the application needs, but the load should not exceed 0.5 W.

5.3 High Voltage Isolation

The UCC12050DVE is capable of supporting reinforced isolation. To this end, the PCB in the UCC12050DVE is designed to demonstrate proper layout techniques to enable reinforced isolation. The channel distance between the primary and secondary side (including the GNDP to GNDS planes and VINP to VISO distance) satisfies requirements for minimum required creepage and clearance distances to maintain reinforced isolation barrier between the input side to the output side.

**Note**

This EVM is not intended for high voltage isolation testing, but merely to demonstrate proper isolation board design.

5.4 Enabling and Disabling the UCC12050

The enable/disable function is easily evaluated using the jumper, J2. Connect the shunt between EN and VINP to enable the UCC12050. Connect the shunt between EN and GNDP to disable the UCC12050 and place it in a low-power state.

5.5 SYNC and SYNC_OK Functionality

J3 is provided to connect an external clock to the UCC12050. In order to synchronize multiple UCC12050 devices to a single clock source, connect an external oscillator (a function generator) between SYNC and GNDP. The oscillator must be a 0 V to 5 V square wave at a frequency of double the desired switching frequency with a 50% duty cycle. The frequency must be within the specified operating range of the device, 14.4 MHz - 17.6 MHz.

The SYNC_OK output, J4, indicates when a valid clock source is connected to SYNC_OK. SYNC_OK is high impedance when a valid clock is connected, and pulled to GNDP when no clock, or an invalid clock, is connected to SYNC. SYNC_OK is pulled up to VINP on the EVM. R2 pads are available to place a termination resistor on SYNC, if needed.

5.6 Output Voltage Selection

The SEL input determines the output voltage regulation threshold of VISO. The UCC12050EVM-022 provides J5 to easily select between the different output voltage selections. J5 is clearly labeled to easily identify the jumper position required for the desired output voltage. For reference, the SEL connection required to achieve a particular ISO regulation is provided in Table 5-1. The device interprets the SEL pin as part of the startup routine, so the SEL state at startup is used to set the regulation point. Any change to J5 has no effect during operation. To change the output voltage regulation, it is required to disable the device (or power down), change the shunt to the desired position, then enable (or power on) the UCC12050.
Table 5-1. Output Voltage Regulation Selections

<table>
<thead>
<tr>
<th>SEL Position</th>
<th>Output Voltage</th>
</tr>
</thead>
<tbody>
<tr>
<td>SEL connected directly to VISO</td>
<td>5.0 V</td>
</tr>
<tr>
<td>SEL connected to VISO through 100 kΩ</td>
<td>5.4 V</td>
</tr>
<tr>
<td>SEL connected to GNDS through 100 kΩ</td>
<td>3.7 V</td>
</tr>
<tr>
<td>SEL connected directly to GNDS</td>
<td>3.3 V</td>
</tr>
</tbody>
</table>

5.7 Test Points: TP1, TP2 & TP3

Test points for VINP, VISO, and SYNC are provided on the EVM.

To get the cleanest measurement of output ripple using an oscilloscope, use probe tip with a ground spring. This reduces the added noise that is introduced when using the longer alligator clip style ground lead. Figure 5-1 shows a picture illustrating how these test points are best used.

Comparison scope shots between the two grounding methods are shown in Figure 5-2.

Figure 5-1. Using the Pig Tail Test Points: TP1, TP2, TP3
5.8 Board Level EMI Mitigation Techniques

The UCC12050EVM-022 board layout is optimized for EMI performance. One EMI mitigation technique demonstrated is an interlayer stitching capacitor (shown as C5 in the schematic). The GNDP and GNDS planes on the inner layers (layer 2 and layer 3) are overlapped in order to form a common-mode, capacitive filter between the two ground planes. GNDP on layer 2 and GNDS on layer 3 overlap. Note that the GND planes do not go all the way to the edge of the board where they overlap. This is to illustrate how to satisfy isolation requirements. There is sufficient distance between the edge of the overlapping layers using this methodology. This only must be used when the planes overlap close to the edge of the board. The second EMI mitigation technique used is the use of stitch vias in the GND planes (GNDP and GNDS) to further suppress EM transmissions.
## 6 List of Materials

### Table 6-1. List of Materials

<table>
<thead>
<tr>
<th>Designator</th>
<th>Qty</th>
<th>Description</th>
<th>Part Number</th>
<th>Manufacturer</th>
</tr>
</thead>
<tbody>
<tr>
<td>C1, C4</td>
<td>2</td>
<td>Capacitor, ceramic, 10 uF, 16 V, +/- 10%, X7R, 0805</td>
<td>CL21B106KOQNNNE</td>
<td>Samsung Electro-Mechanics</td>
</tr>
<tr>
<td>(C1, C4)-alternate</td>
<td>0</td>
<td>Capacitor, ceramic, 10 uF, 16 V, +/- 10%, X7S, 0805, AEC-Q200</td>
<td>CL21Y106KOQ4PNE</td>
<td>Samsung Electro-Mechanics</td>
</tr>
<tr>
<td>C2, C3</td>
<td>2</td>
<td>Capacitor, ceramic, 0.1 µF, 50 V, +/- 10%, X7R, AEC-Q200 Grade 1, 0603</td>
<td>0603SC104KA2Z2A</td>
<td>AVX</td>
</tr>
<tr>
<td>J1, J6</td>
<td>2</td>
<td>Conn term block, 2POS, 3.81mm, TH</td>
<td>1727010</td>
<td>Phoenix Contact</td>
</tr>
<tr>
<td>J2</td>
<td>1</td>
<td>Header, 100 mil, 3x1, Tin, TH</td>
<td>PEC03SAAN</td>
<td>Sullins Connector Solutions</td>
</tr>
<tr>
<td>J3, J4, J5</td>
<td>3</td>
<td>Header, 100 mil, 2x1, Tin, TH</td>
<td>PEC02SAAN</td>
<td>Sullins Connector Solutions</td>
</tr>
<tr>
<td>R1, R3</td>
<td>2</td>
<td>Resistor, 100 kΩ, 5%, 0.063 W, AEC-Q200 Grade 0, 0402</td>
<td>CRCW0402100KJNED</td>
<td>Vishay-Dale</td>
</tr>
<tr>
<td>R2</td>
<td>0</td>
<td>Termination resistor for SYNC, 0402, DNP</td>
<td></td>
<td></td>
</tr>
<tr>
<td>R4</td>
<td>0</td>
<td>Load resistor, 0805, DNP</td>
<td></td>
<td></td>
</tr>
<tr>
<td>TP4, TP5</td>
<td>2</td>
<td>Test point, Miniature, SMT</td>
<td>5019</td>
<td>Keystone</td>
</tr>
<tr>
<td>U1</td>
<td>1</td>
<td>500 mW, High-Efficiency, Low-Emissions, 5 kVRMS Isolated DC/DC Converter, DVE0016A (SO-MOD-16)</td>
<td>UCC12050DVE</td>
<td>Texas Instruments</td>
</tr>
<tr>
<td>U1-alternate</td>
<td>0</td>
<td>500 mW, High-Efficiency, Low-Emissions, 3 kVRMS Isolated DC/DC Converter, DVE0016A (SO-MOD-16)</td>
<td>UCC12040DVE</td>
<td>Texas Instruments</td>
</tr>
<tr>
<td>U1-alternate</td>
<td>0</td>
<td>500 mW, High-Efficiency, Low-Emissions, 3 kVRMS Isolated DC/DC Converter AEC-Q100, DVE0016A (SO-MOD-16)</td>
<td>UCC12041QDVERQ1</td>
<td>Texas Instruments</td>
</tr>
<tr>
<td>U1-alternate</td>
<td>0</td>
<td>500 mW, High-Efficiency, Low-Emissions, 5 kVRMS Isolated DC/DC Converter AEC-Q100, DVE0016A (SO-MOD-16)</td>
<td>UCC12051QDVERQ1</td>
<td>Texas Instruments</td>
</tr>
<tr>
<td>FID1, FID2, FID3</td>
<td>0</td>
<td>Fiducial mark. There is nothing to buy or mount.</td>
<td>N/A</td>
<td>N/A</td>
</tr>
</tbody>
</table>
8 Layout Diagrams

Figure 8-1. Top Layer Composite
Figure 8-2. Signal Layer 1
Figure 8-3. Signal Layer 2
9 Revision History
NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision C (June 2021) to Revision D (February 2022)  Page
• Updated EN description........................................................................................................5

Changes from Revision B (January 2021) to Revision C (June 2021)  Page
• Added UCC12041QDVERQ1 to Table 1-1 ................................................................................2
• Changed UCC12051DVE-Q1 to UCC12051QDVERQ1 in Table 1-1 ........................................2
• Updated the surge voltage for UCC12040DVE in Table 1-1 ...................................................2
• Added UCC12041QDVERQ1 to Table 6-1 .................................................................................9
• Changed UCC12051DVE-Q1 to UCC12051QDVERQ1 in Table 6-1 ..........................................9

Changes from Revision Original (January 2021) to Revision B (January 2021)  Page
• Updated device links..........................................................................................................1

Changes from Revision Original (September 2019) to Revision A (January 2021)  Page
• Added details to support UCC12040 and the UCC12051-Q1...................................................1

Figure 8-4. Bottom Layer
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